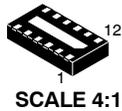


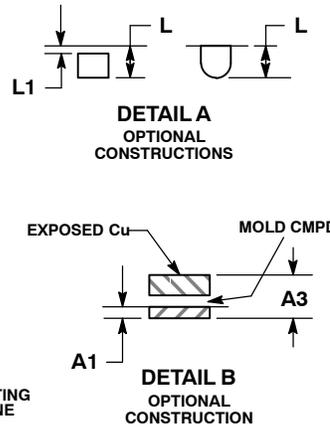
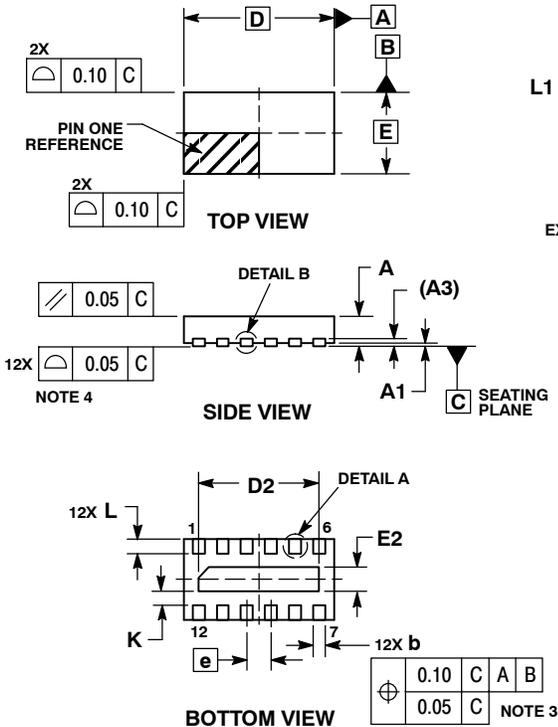
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



UDFN12, 2.5x1.35, 0.4P
CASE 517BD-01
ISSUE O

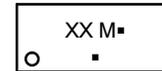
DATE 18 NOV 2009



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 mm FROM THE TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| MILLIMETERS | | |
|-------------|------|------|
| DIM | MIN | MAX |
| A | 0.45 | 0.55 |
| A1 | 0.00 | 0.05 |
| A3 | 0.13 | REF |
| b | 0.15 | 0.25 |
| D | 2.50 | BSC |
| D2 | 1.90 | 2.10 |
| E | 1.35 | BSC |
| E2 | 0.30 | 0.50 |
| e | 0.40 | BSC |
| K | 0.15 | --- |
| L | 0.20 | 0.30 |
| L1 | --- | 0.05 |

GENERIC MARKING DIAGRAM*



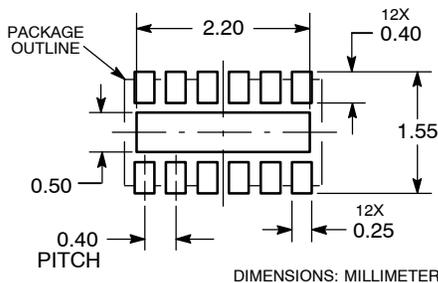
1

- XX = Specific Device Code
M = Month Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|------------------|---------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | UDFN12, 2.5X1.35, 0.4P | PAGE 1 OF 2 |

